

NOTE:

1.MATERIAL:

Housing: Polyplastics,LCP E130I UL94V-0, Color: Black

Contact: Beryllium Copper (C1720 1/2H) ; T=0.15mm

Tab Pad: Phospor Bronze (C5210 H) ; T=0.15mm

2.FINISH:

Contact Spring:

Clean parts per ASTM B733 (150 microinches minimum),SC1,TYPE1,CLASS 5

50u" Hard Gold:Gold plate per ASTM B488,TYPE 2,GRADE C(130-200KNOOP),

Class 1.25 (50 microinches minimum)

Tab Pad:

Matte Sn 100u"

3.Solder Heat Resistance: Reflow Soldering 260° For 10SEC.

4.For Reflow Soldering LEE Free Process.

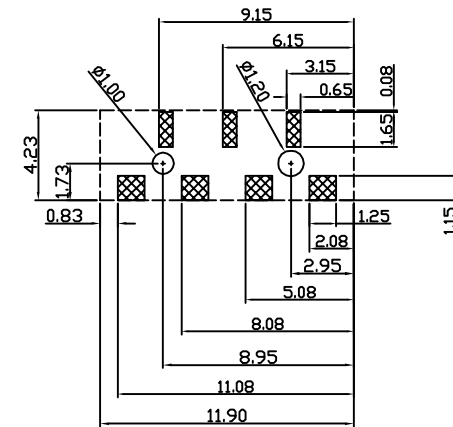
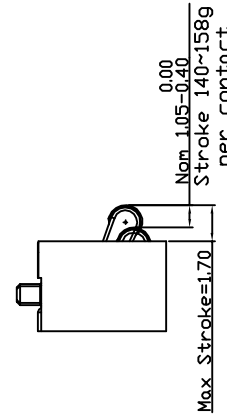
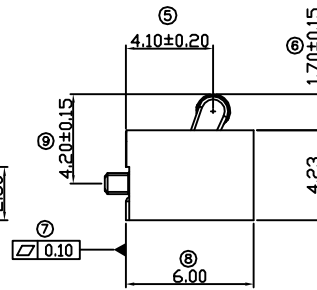
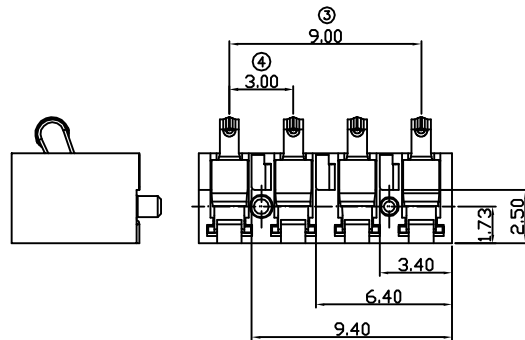
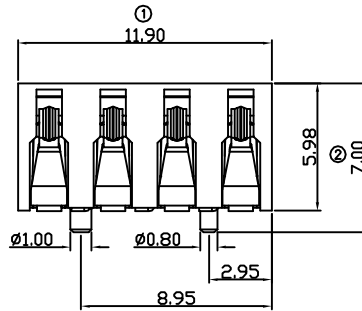
5.Preparation of Copper and Copper-Based Alloys for Electroplating.

6.Compression force :

Min compression @0.65mm Force:≥100g

Norm compression @1.05 mm Force:140~158g

Max compression @1.45mm Force:200~250g

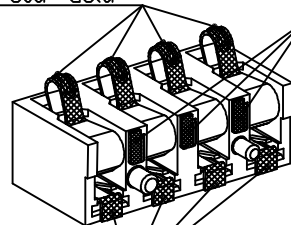


RECOMMENDED PC BOARD LAYOUT

Contact 50u" Gold

Matte Sn 100u"

Contact 1u" Gold



RoHS Compliant

TOLERANCES ARE

MORETHANALL
PCB CONNECTORS
Cable ASSEMBLIES

煜倫股份有限公司

www.morethanall.com

DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm

SCALE 1 : 1

DATE

SIZE A4

X. ± 0.50

.X ± 0.30

.XX ± 0.20

.XXX ±

ANG ±

PPOJECTION

照片框

ORDER INFORMATION

BCS30-W60EP24-04-LF

SERIES

LEADFREE

04 WAY

4.10mm

POST

90°SMT

EAR

HIGH 6.0mm

DESCRIPTION: